



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re the Application of

Masahiko YANAGISAWA

Group Art Unit: 2826

Application No.: 09/674,924

Examiner: A. Williams

Filed: November 8, 2000

Docket No.: 105013

For: A FLEXIBLE INTERCONNECT SUBSTRATE OF A TAPE-SHAPED
SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE AND CIRCUIT
BOARD, AND METHOD OF MAKING SAME (As Amended)

#12/ Muelh
ANDAM
10/22/02

AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the May 8, 2002 Office Action, please amend the above-identified
application as follows:

IN THE TITLE:

Please replace the title so that it reads as follows:

A FLEXIBLE INTERCONNECT SUBSTRATE OF A TAPE-SHAPED
SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE AND CIRCUIT BOARD,
AND METHOD OF MAKING SAME

IN THE CLAIMS:

Please replace claims 1-3 and 6-8 as follows:

1. ~~(Amended)~~ A flexible interconnect substrate comprising:
a tape-shaped base substrate; and
an interconnect pattern formed on the base substrate,

B1 Sub C2